

L Number	Hits	Search Text	DB	Time stamp
1	12	(electrodeposition adj layer) with hole	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 15:39
2	3	5430421.URPN.	USPAT	2004/02/22 15:38
3	17	(electrodeposition adj layer) same hole	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 15:40
4	37	(electrodeposition adj layer) and hole	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 15:49
5	12	3623961.URPN.	USPAT	2004/02/22 15:47
6	140768	multilayer	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 15:50
7	39198	multilayer and (hole or (through adj hole) or via)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 18:03
9	7	(multilayer and (hole or (through adj hole) or via)) and (electrodeposition adj layer)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 15:51
10	22	("3469982" "3857681" "3981691" "3984598" "3998601" "4049431" "4049481" "4082620" "4088544" "4705592" "4808967" "4863808" "5017271" "5242562" "5243320" "5366814" "5389446" "5403672" "5437914" "5456817" "5482784" "5681443").PN.	USPAT	2004/02/22 15:52
8	531	(multilayer and (hole or (through adj hole) or via)) and (electrodeposition or (electrodeposition adj layer))	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 16:28
11	12	5218472.URPN.	USPAT	2004/02/22 16:28
12	531	(multilayer and (hole or (through adj hole) or via)) and electrodeposition	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 16:29
13	201	((multilayer and (hole or (through adj hole) or via)) and electrodeposition) and electroplating	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 16:57
14	31	174/263-266.ccls. and electrodeposition	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 17:39
15	8	("5106473" "5183552" "5194313" "5300208" "5356511" "5368717" "5403467" "5427841").PN.	USPAT	2004/02/22 16:59
16	3	5528000.URPN.	USPAT	2004/02/22 17:00
17	5	("4218498" "5415762" "5528000" "5648125" "5667662").PN.	USPAT	2004/02/22 17:01
18	0	6123995.URPN.	USPAT	2004/02/22 17:01
19	13	("4388136" "4545119" "4668532" "4891069" "4970624" "5045381" "5047114" "5435877" "5450290" "5495394" "5528000" "5640047" "5672226").PN.	USPAT	2004/02/22 17:01
20	4	6083340.URPN.	USPAT	2004/02/22 17:03
21	7	3357099.URPN.	USPAT	2004/02/22 17:06
22	30	5245751.URPN.	USPAT	2004/02/22 17:08

23	4	((("6515237") or ("6637105")).PN.	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 17:57
24	4	("5444189" "5981043" "6000129" "6326561").PN.	USPAT	2004/02/22 17:45
25	2	("4374868" "5072075").PN.	USPAT	2004/02/22 17:48
26	4	5444189.URPN.	USPAT	2004/02/22 17:49
27	4	("4387006" "5444189" "6376052" "6420017").PN.	USPAT	2004/02/22 17:50
28	4	("4816323" "5346750" "5766670" "6010768").PN.	USPAT	2004/02/22 17:52
29	12	("4574371" "4752499" "4927983" "5021472" "5055321" "5227012" "5344893" "5447996" "5519177" "5589255" "5688583" "5741575").PN.	USPAT	2004/02/22 17:53
30	186	174/263-266.ccls. and electroplating	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 17:58
31	18	(174/263-266.ccls. and electroplating) and electrodeposition	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 17:59
32	15	((174/263-266.ccls. and electroplating) and electrodeposition) and @pd<=20010228	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 18:02
33	9	("0844304" "2474502" "3011920" "3934335" "4303798" "4325780" "4919768" "5007990" "5017742").PN.	USPAT	2004/02/22 18:00
34	12	5276290.URPN.	USPAT	2004/02/22 18:01
35	25501	electrodeposition and @pd<20010228	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 18:02
36	4031	(electrodeposition and @pd<20010228) and (hole or (through adj hole) or via)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 18:03
37	1087	((electrodeposition and @pd<20010228) and (hole or (through adj hole) or via)) and electroplating	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 18:04
38	2761	((electrodeposition and @pd<20010228) and (hole or (through adj hole) or via)) and thickness	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 18:03
39	878	((electrodeposition and @pd<20010228) and (hole or (through adj hole) or via)) and thickness) and electroplating	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 18:04
40	676	((electrodeposition and @pd<20010228) and (hole or (through adj hole) or via)) and thickness) and electroplating) and (substrate or board or multilayer)	USPAT; EPO; JPO; DERWENT; USOCR	2004/02/22 18:04